

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

THERMOPLASTIC MOLDING PROCESS AND APPARATUS

the specification of which

X is attached hereto.
_____ was filed on _____ as
Application Serial No. _____
and was amended on _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulation, 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			<u>Priority Claimed</u>	
<u>N/A</u>				
(Number)	(Country)	Day/Month/Year	Yes	No
_____	_____	_____	_____	_____
(Number)	(Country)	Day/Month/Year	Yes	No
_____	_____	_____	_____	_____
(Number)	(Country)	Day/Month/Year	Yes	No
_____	_____	_____	_____	_____

I hereby claim the benefit under Title 35, United States Code, 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

NA
(Application Serial No.) (Filing Date) (Status)
(patented, pending, abandoned)

(Application Serial No.) (Filing Date) (Status)
(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

William M. Hobby, III, Registration No. 24,167

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FIRST INVENTOR

Dale E. Polk, Jr.

Full name of sole or first inventor

12/8/97
Date

Dale E. Polk, Jr.
First Inventor's signature

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Residence

U.S.A.

Citizenship

Same as above

Post Office Address

20095516 9T5E5580

Applicant or Patentee: DALE E. POLK, JR.
Serial or Patent No.: _____
Filed or Issued: _____
For: THERMOPLASTIC MOLDING PROCESS AND APPARATUS

**VERIFIED STATEMENT (DECLARATION) CLAIMING SMALL ENTITY STATUS
(37 CFR 1.9(f) and 1.27(b) - INDEPENDENT INVENTOR)**

As a below named inventor, I hereby declare that I qualify as an independent inventor as defined in 37 CFR 1.9(c) for the purpose of paying reduced fees under Section 41(a) and (b) of Title 35, United States Code, to the Patent and Trademark Office with regard to the invention entitled THERMOPLASTIC MOLDING PROCESS AND APPARATUS described in:

- (X) the application filed herewith
() application Serial No. _____, filed _____
() Patent No. _____, issued _____

I have not assigned, granted, conveyed or licensed and am under no obligation under contract or law to assign, grant, convey or license, any rights in the invention to any person who could not be classified as an independent inventor under 37 CFR 1.9(c) if that person had made the invention, or to any concern which would not qualify as a small business concern under 37 CFR 1.9(d) or a nonprofit organization under 37 CFR 1.9(e).

Each person, concern or organization to which I have assigned, granted, conveyed or licensed or am under an obligation under contract or law to assign, grant, convey, or license any rights in the invention is listed below:

- (x) no such person, concern, or organization
() persons, concerns or organizations listed below*

*NOTE: Separate verified statements are required from each named person, concern, or organization having rights to the invention averring to their status as small entities. (37 CFR 1.27)

FULL NAME N/A
ADDRESS _____

() Individual () Small Business Concern () NonProfit Organization

I acknowledge the duty to file, in this application or patent, notification of any change in status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR 1.28(b)).

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12/08/97
Date

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